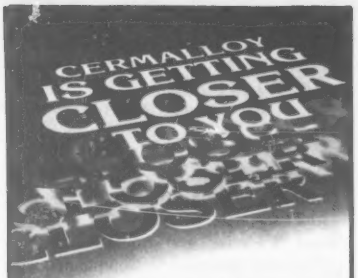

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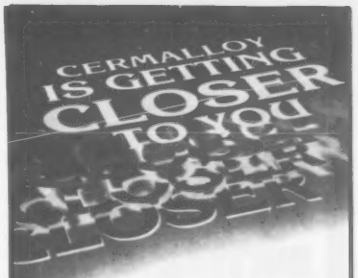
Circle 51 on Reader-Service Card

Circuitry," C.W. Brooks, M.R. Lucas, June, pg 151.
"Electronic Packaging for an Artillery Delivered Sensor," Miles J. Kurina, June, pg 158.
"Considerations in Device Cooling," EPP Staff Report, July, pg 304.
"Principles of Switching Power Supplies," Robert H. Okada, July, pg 328.
"Bus Bar Applications," Dallas Erickson, Aug., pg 68.
"Considerations in Device Cooling," EPP Staff Report, Aug., pg 109.
"Guide to Broaching Fasteners," Richard B. Ernst, Aug., pg 125.
"High Lead Count Packaging and Interconnection Alternatives," B.M. Hargis, D.J. Westervelt, Sept., pg 82.
"Packaging High-Power LSI Devices in High-Speed Computer Systems, Jeff Bohn, Sept., pg 92.
"Wireform Construction for Electronic Instrument Packaging," Tom Saucy, Oct., pg 175.
"Reliability and Application of Leaded Plastic Chip Carriers," W.L. Brodsky, F.D. Parker, J.W. Stafford, Nov., pg 109.
"Packaging Semiconductors for Optimum Optical Coupling, William Schumacher, Nov., pg 94.
"Packaging Avionics at Sperry Flight Systems," Howard W. Markstein, Nov., pg 146.
"New Assembly Ideas Spurred by Easy Bonding," Dec., pg 198.
"Design Center Takes Shortcut from Prototype to Production," Gerald Blume, Dec., pg 204.

Printed Circuit Fabrication

"Dry Film Photoresist Performance on Electroless Copper," William L. Hamilton, Jan., pg 232.
"Reliability Considerations in Flex-Rigid Circuits," Richard T. Lamoureux, Jan., pg 243.
"An Evaluation of High Energy Bonding for PC Board Repair," C.F. Hornig, Jan., pg 251.
"Considerations in Producing High Density PC Boards," Howard W. Markstein, March, pg 47.
"Very Fine Line Imaging," William W. Burr, March, pg 126.
"Conveyorizing NTI's PC Board Manufacturing Increases Output Five-Fold," March, pg 188.
"Metriform Fabrication Spurs Development of High Density Circuits," R. Burke, L.R. Volpe, D.A. Zeskind, May, pg 69.
"Update on PC Exposure Equipment," Howard W. Markstein, June, pg 45.
"Mass Lamination: The Laminator's Expanding Role," Howard W. Markstein, July, pg 67.
"Water soluble Flux and Its Effect on PC Board Insulation Resistance," Jack Brous, July, pg 79.
"A New Manufacturing Technique for Flexible Circuitry," E.W. Brooman, G.R.



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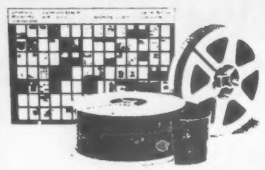

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Schaer, Aug., pg 147.
"The Application of Ultrasonics to the Resist Stripping Process," Robert Deitz, Oct., Pg 185.
"The Soldering Performance of Fluxes: A Study," M.P. Cassidy, K.M. Lin, Nov., pg 153.
"Wave Solder Process Controls," M.H. Bester, Dec., pg 99.
"A New Process for Patterning Printed Wiring Boards," William M. Beckenbaugh, Donald Dinella, Ted D. Polakowski, Dec., pg 76.

Production Techniques
"New Developments in CAD/CAM Technology," Leonard Marks, Feb., pg 40.
"Recent Advances in Abrasive Trimming and Material Removal Techniques," Herb Weightman, March, pg 111.
"Automated Component Insertion for Flexible Circuits," W. Adams, R. Bell, April, pg 153.
"Guidelines for Selection of Hand Tools-Cutters and Pliers," Howard Gittleson, July, pg 28.
"Flux Dam Aids Cleaning Under Chip Capacitors," Donald H. Daebler, Sept., pg 131.
"Computer Generated Programs and Processes for Automatic Assembly Equipment," Jack Stelhorn, Nov., pg 129.
"New Assembly Ideas Spurred by Easy Bonding," Dec., pg 198.

Soldering/Welding/Fastening
"Evaluating Organic Fluxes," Charles S. McElwee, Jan., pg 269.
"Mass Soldering and Aqueous Cleaning Processes Operated in Compliance with Water Pollution Regulations," Stan Berstein, James M. Green, March, pg 170.
"Wire termination: the State of the Art," Dallas Erickson, April, pg 63.
"Ensuring Successful PC Board Soldering," Howard W. Markstein, May, pg 53.
"Laser Microsoldering," F. Burns, C. Zyetz, May, pg 109.
"Trends in Automatic PC Soldering," Dallas Erickson, June, pg 65.
"Reliable Wavesoldering of Chip Components," William H. Down, July, pg 171.
"The Kinetics of the Soldering Process," B.M. Allen, July, pg 288.

Testing and Inspection
"Interpretation of Corona Measurements on High Voltage Assemblies," William G. Dunbar, Jan., pg 139.
"Signature Analysis and Test Strategy," James K. Skilling, Jan., pg 151.
"Incoming Inspection of Analog/Digital

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Devices," Howard W. Markstein, Feb., pg 63.
"In Circuit Testing of LSI Components," Bruce Barnett, John Hughes, Feb., pg 79.
"A New Concept in Data Highway Technology," Feb., pg 173.
"Component Verification System." R.E. Hines, D.D. Schroeder, March, pg 85.
"Combined Analog/Digital Testing of Line Cards and Associated Components," William Attridge, March, pg 148.
"Functional Testing Using Vacuum Fixtures," Gary E. Miller, March, pg 157.
"ATE Fixturing Techniques for Hybrid Board Test," P. Zeischang, S. Rayburn, April, pg 163.
"In-Circuit Test Programming: Do It Yourself?" G. Kinsey, April, pg 171.
"Economics of Functional Testing at Selected Levels," H. Frank Binnendyk, May, pg 187.
"Test Defect Reporting," William Spiker, II, June, pg 166.
"Functional Board Testing: The Alternatives for Increased Throughput," K. Taschiouglou, H.S. Lahman, June, pg 173.
"The Effects of Voltage Levels Used in Testing Printed Circuit Assemblies," Ralph D. Taylor, July, pg 209.
"In-Circuit Test in the High Volume Production Environment," S. Sanderson, July, pg 239.
"Static Control in Bare Board Testing," James E. Berry, Aug., pg 161.
"New Thermometry Technique Measures Component Temperature," Kenneth A. Wickersheim, Sept., pg 121.
"Dedicated LSI Testers," Chris Chrones, Oct., pg 37.
"Modern In-Circuit/Functional Test Systems," Howard W. Markstein, Oct., pg 55.
"Thermography Testing of Production PC Boards," Merle Weight, Oct., pg 69.
"Controlled Temperature Testing of Electronic Components," Taylor N. Thompson, Oct., pg 135.
"Can ATE be Trusted by QC?" Allan C. Stover, Oct., pg 140.
"Modularity in Test Systems: A Key to Meeting Unique Customer Requirements," Al Esser, Oct., pg 161.
"Reliability Tests on Detergent Cleaned FR-4 Coupons," L.J. Turbini, D.W. Rudd, B.A. Walsh, Dec., pg 190.

Wire and Cable

"Ribbon Cable/Connector Update," Howard W. Markstein, April, pg 49.
"Use of Coaxial Plenum Cable for High Speed Data Transmission," Joseph Weiss, June, pg 145.

INDEX OF AUTHORS

Adams, William, April, pg 153.
Agnihotri, K., April, pg 179.
Allen, B.M., July, pg 288.
Amey, Daniel I., July, Pg 177.
Anslow, J.W., May, pg 158.
Antonetti, Vincent W., Jan., pg 259.
Attridge, William, March, pg 148.
Barnett, Bruce, Feb., pg 79.
Beckenbaugh, William M., Dec., pg 76.
Bell, Richard, April, pg 153.
Berry, James E., Aug., pg 161.
Bernstein, Stan, March, pg 170.
Bester, M.H., Dec., pg 99.
Binnendyk, H. Frank, May, pg 187.
Blume, Gerald, Dec., pg 204.
Bohn, Jeff, Sept., pg 92.
Bowen, Terry, Sept., pg 140.
Braun, J.A., March, pg 180.
Brodsky, W.L., April, pg 124; Nov, pg 109
Brooks, C.W., June, pg 151.
Brooman, E.W., Aug., pg 147.
Brous, Jack, July, pg 79.
Burke, R., May, pg 69.
Burns, F., May, pg 109.
Burr, William W., March, pg 126.
Cassidy, M.P., Nov., pg 153.
Chrones, Chris, Oct., pg 37.
Coppenrath, Lawrence F., Feb., pg 97.
Daebler, Donald H., April, pg 99; Sept., pg 131.
Deitz, Robert, Oct., pg 185.
Dieffenbacher, G.W., Jan., pg 113.
Dinella, Donald, Dec., pg 76.
Doty, P., May, pg 97.
Down, William H., July, pg 171.

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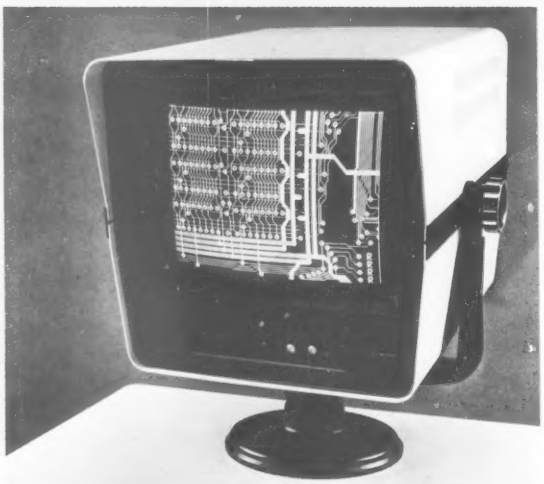

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Circle 130 on Reader-Service Card

Dunbar, William, Jan., pg 139.
EPP Staff Report, July, pg 304; Aug, pg 109.
Esser, Al., Oct., pg 161.
Erickson, Dallas, March, pg 64; April, pg 63; June, pg 65; Aug, pg 68; Nov., pg 57.
Ernst, Richard B., Aug., pg 125.
Fennimore, John E., May, pg 172.
Gittleson, Howard G., July, pg 28.
Grayson, C. Jackson, Sept., pg 47.
Green, James M., Jan., pg 170.
Gustavson, G.E., May, pg 97.
Hamilton, William L., Jan., pg 232.
Hargis, B.M., Sept., pg 82.
Harper, C.A., Aug., pg 134.
Hines, R.E., March, pg 85.
Hornig, C.F., Jan., pg 251.
Hughes, John, Jan., pg 79.
Hwang, Un Pah, Jan., pg 259.
Keller, Charles J., Jan., pg 259.
Kinsey, G., April, pg 171.
Kurina, Miles J., June, pg 158.
Lahman, H.S., June, pg 173.
Lamoureux, Richard T., Jan., pg 243.
Lassen, C.L., March, pg 98.
Lin, K.M., Nov., pg 153.
Lindberg, Frank A., Feb., pg 137.
Lucas, M.R., June, pg 151.
Mackay, C.A., Feb., pg 116.
Marks, Leonard, Feb., pg 40.
Markstein, Howard W., Jan., pg 65; Feb., pg 63; March, pg 47; April, pg 59; May, pg 53; June, pg 45; July, pg 67; Aug, pg 51; Sept., pg 50; Oct., pg 55; Nov., pg 35, 146; Dec., pg 41.
McElwee, Charles, Jan., pg 269.

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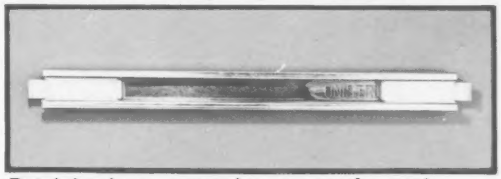

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Circle 79 on Reader-Service Card

McManus, Paul E., Feb., pg 97.
Miller, Gary E., March, pg 157.
O'Neill, Timothy G., Jan., pg 39; May, pg 79.
Okada, Robert H., July, pg 328.
Parker, F.D., April, pg 124; Nov., pg 109.
Phillips, Howard E., July, pg 147.
Polakowski, Ted. D., Dec., pg 76.
Rayburn, S., April, pg 163.
Rudd, D.W., Dec., pg 190.
Rydwansky, Jr., F.C., March, pg 180.
Sakaguchi, Ed, Aug., pg 93.
Sanderson, S., July, pg 239.
Saucy, Tom, Oct., pg 175.
Schaer, G.R., Aug., pg 147.
Schelhorn, Robert L., Jan., pg 83.
Schoenthaler, D., April, pg 124.
Schroeder, D.D., March, pg 111.
Schumacher, William, Nov., pg 94.
Sergent, Jerry E., Sept., pg 65.
Shankin, Morris, Jan., pg 98.
Skilling, James L., Jan., pg 151.
Slattery, James A., Oct., pg 146.
Spiker, II, William, June, pg 166.
Stafford, J.W., Nov., pg 109.
Staley, W.W., Aug., pg 134.
Stelhorn, Jack, Nov., pg 129.
Stover, Allan C., Oct., pg 140.
Strom, Steve, April, pg 115.
Stubin, R.J., Jan., pg 113.
Taylor, Ralph D., July, pg 209.
Taschiouglou, K., June, pg 173.
Thompson, Taylor N., Oct., pg 135.
Turbini, Laura J., Dec., pg 190.
VanWert, Bernard, July, pg 128.
Volpe, L.R., May, pg 69.
Walsh, B.A., Dec., pg 190.
Weight, Merle, Oct., pg 69.
Weightman, Herb, March, pg 111.
Weiss, Joseph, June, pg 145.
Wenthen, F., May, pg 158.
Westervelt, D.J., Sept., pg 82.
White, C.E.T., Oct., pg 146.
Whitley, J.H., July, pg 269.
Wickersheim, Kenneth A., Sept., pg 121.
Wilson, E.A., April, pg 139.
Zeroth, Jerry C., July, pg 113.
Zeskind, D.A., May, pg 69.
Zieschang, P., April, pg 163.
Zyetz, C., May, pg 109.

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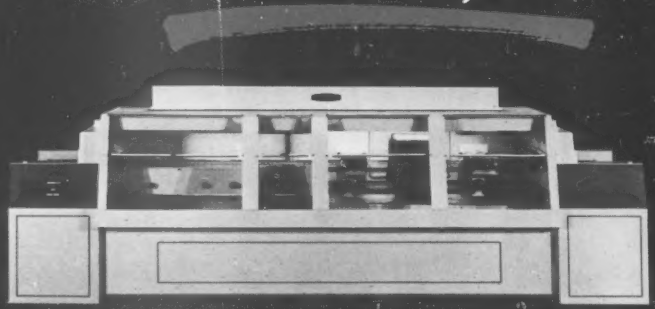

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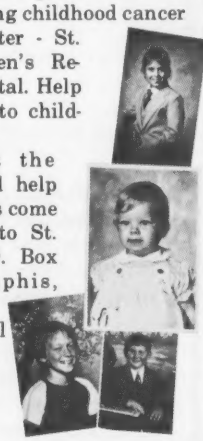

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